



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20120822000A
Qualification of Mold Compound 4211471 and Mount Compound 4211470
for Select Devices Assembled in TI-Malaysia and TI-Taiwan
using TSSOP package
Change Notification / Sample Request**

Date: 10/5/2012
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **180** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN ww admin team@list.ti.com](mailto:PCN_admin_team@list.ti.com)).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120822000A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
8W244AMDGGREPG4	null
CD4504BMPWREP	null
MAX3232MPWREP	null
MSP430G2231QPW1EP	null
SN74AHC08MPWREP	null
SN74AHC14MPWREP	null
SN74AHC244MPWREPG4	null
SN74AHC74MPWREP	null
SN74AHCT00MPWREP	null
SN74AHCT244MPWREP	null
SN74AHCT74MPWREP	null
SN74HC02QPWREP	null
SN74HC10QPWREP	null
SN74HC165QPWREP	null
SN74LV04ATPWREP	null
SN74LV08ATPWREP	null
SN74LV14AMPWREP	null
SN74LV14ATPWREP	null
SN74LV4040AMPWREP	null
SN74LV595AIPWREP	null
SN74LVC00AMPWREP	null
SN74LVC07AIPWREP	null
SN74LVC08AMPWREP	null
SN74LVC125AIPWREP	null
SN74LVC138AQPWREP	null
SN74LVC14AQPWREP	null
SN74LVC32AMPWREP	null
SN74LVC32AMPWREPG4	null
SN74LVC4245AIPWREP	null
SN74LVC74AMPWREP	null
SN74LVC74AQPWREP	null
SN74LVC8T245MPWREP	null
TLV2548MPWREP	null
V62/03662-01XE	null
V62/04655-02YE	null
V62/04659-01YE	null
V62/04669-02YE	null
V62/04671-01XE	null
V62/07630-01XE	null
V62/09615-01XE	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20120822000A		PCN Date:	10/05/2012										
Title:	Qualification of Mold Compound 4211471 and Mount Compound 4211470 for Select Devices Assembled in TI-Malaysia and TI-Taiwan using TSSOP package													
Customer Contact:	PCN_ww_admin_team@list.ti.com		Phone:	+1(214)480-6037	Dept: Quality Services									
Proposed 1st Ship Date:		04/05/2013		Estimated Sample Availability:	Date provided at sample request.									
Change Type:														
☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials									
☐	Design	☐	Electrical Specification	☐	Mechanical Specification									
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process									
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process									
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process									
PCN Details														
Description of Change:														
Qualification of Mold Compound 4211471 and Mount Compound 4211470 for HPA-PWR Select Devices Assembled in TI-Malaysia and TI-Taiwan using TSSOP package. Devices will remain in their current assembly facility and material differences are shown in the following table:														
<table border="1" style="width: 100%;"> <tr> <th style="width: 33%;"></th> <th style="width: 33%; text-align: center;">Change From:</th> <th style="width: 33%; text-align: center;">Change To:</th> </tr> <tr> <td>Mount Compound</td> <td style="text-align: center;">4042500</td> <td style="text-align: center;">4211470</td> </tr> <tr> <td>Mold Compound</td> <td style="text-align: center;">4209002</td> <td style="text-align: center;">4211471</td> </tr> </table>							Change From:	Change To:	Mount Compound	4042500	4211470	Mold Compound	4209002	4211471
	Change From:	Change To:												
Mount Compound	4042500	4211470												
Mold Compound	4209002	4211471												
Qual Results are provided in the Qual Data Section.														
Reason for Change:														
Continuity of supply.														
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):														
None.														
Changes to product identification resulting from this PCN:														
None.														
Product Affected:														
8V182512IDGGREP	SN74LV165AMPWREP	V62/03618-02UE	V62/04689-01YE											
8W244AMDGGREPG4	SN74LV32AMPWREP	V62/03618-04UE	V62/04691-01XE											
CAHCT244MPWREPG4	SN74LV32ATPWREP	V62/03619-07ZE	V62/04692-01XE											
CALVC164245IDGGREP	SN74LV374ATPWREP	V62/03645-01XE	V62/04693-01XE											
CALVC164245MDGGREP	SN74LV393ATPWREP	V62/03646-01XE	V62/04693-02XE											
CCBTLV3257MPWREP	SN74LV4040AMPWREP	V62/03647-01XE	V62/04694-01XE											
CD4504BMPWREP	SN74LV4051ATPWREP	V62/03648-01XE	V62/04695-01XE											
CD74HC4017QPWREP	SN74LV4052ATPWREP	V62/03649-01XE	V62/04696-01XE											
CD74HCT574QPWREP	SN74LV4053ATPWREP	V62/03650-01XE	V62/04698-01XE											
CLVC16244AIDGGREP	SN74LV595AIPWREP	V62/03651-01XE	V62/04700-01XE											
CLVCC3245AIPWREP	SN74LV74AMPWREP	V62/03652-01XE	V62/04701-01XE											
CLVCC4245AMPWREP	SN74LV8154MPWREP	V62/03653-01XE	V62/04703-01YE											
CLVCC4245AMPWREPG4	SN74LV86ATPWREP	V62/03654-01XE	V62/04705-01XE											
CLVCH16652AIDGGREP	SN74LVC00AMPWREP	V62/03655-01XE	V62/04706-01XE											
CLVCH16T245MDGGREP	SN74LVC00AMPWREPG4	V62/03656-01XE	V62/04707-01XE											
CLVTH162240IDGGREP	SN74LVC00AQPWREP	V62/03657-01XE	V62/04708-01XE											
CLVTH162244IDGGREP	SN74LVC02AMPWREP	V62/03658-01XE	V62/04709-01XE											
CLVTH162245IDGGREP	SN74LVC04AQPWREP	V62/03659-01XE	V62/04710-01XE											
CLVTH16240IDGGREP	SN74LVC07AIPWREP	V62/03660-01XE	V62/04711-01XE											

CLVTH16244AMDGGREP	SN74LVC07AMPWREP	V62/03660-02XE	V62/04712-01XE
CLVTH16244AQDGGREP	SN74LVC08AMPWREP	V62/03661-01XE	V62/04713-01XE
CLVTH16245AQDGGREP	SN74LVC08AMPWREPG4	V62/03662-01XE	V62/04714-01XE
CLVTH16373IDGGREP	SN74LVC08AQPWREP	V62/03662-02XE	V62/04715-01XE
CLVTH16374IDGGREP	SN74LVC125AIPWREP	V62/03663-01XE	V62/04716-01XE
CLVTH16500IDGGREP	SN74LVC138AMPWTEP	V62/03664-01XE	V62/04717-01XE
CLVTH16501IDGGREP	SN74LVC138AQPWREP	V62/03665-01XE	V62/04718-01XE
CLVTH16543IDGGREP	SN74LVC14AQPWREP	V62/03666-01XE	V62/04719-01XE
CLVTH16646IDGGREP	SN74LVC157AQPWREP	V62/03667-01YE	V62/04723-01XE
CLVTH16652IDGGREP	SN74LVC245AIPWREP	V62/03672-02YE	V62/04724-01XE
CLVTH16835IDGGREP	SN74LVC257AMPWREP	V62/04601-01YE	V62/04730-01XE
CLVTH16952IDGGREP	SN74LVC257AQPWREP	V62/04601-03YE	V62/04737-01XE
CVMEH22501AIDGGREP	SN74LVC32AMPWREP	V62/04602-01YE	V62/04739-01YE
LM239AMPWREP	SN74LVC32AMPWREPG4	V62/04604-01XE	V62/04762-01XE
LM2902KAVMPWREP	SN74LVC32AQPWREP	V62/04604-02XE	V62/05602-01XE
LM2902KAVQPWREP	SN74LVC373AQPWREP	V62/04604-03XE	V62/05606-01XE
MAX3232MPWREP	SN74LVC374AQPWREP	V62/04604-04XE	V62/05612-01YE
MAX3243MPWREP	SN74LVC4245AIPWREP	V62/04604-06XE	V62/05612-02YE
MSP430F2274MDATEP	SN74LVC540AQPWREP	V62/04643-01XE	V62/05615-01XE
SN65LVDS95DGGREP	SN74LVC541AQPWREP	V62/04644-01YE	V62/05615-02XE
SN65LVDT14QPWREP	SN74LVC573AQPWREP	V62/04645-01XE	V62/06602-01XE
SN65LVDT41QPWREP	SN74LVC574AQPWREP	V62/04645-02XE	V62/06603-01XE
SN74ABT541BIPWREP	SN74LVC74AMPWREP	V62/04652-01YE	V62/06605-01XE
SN74AC11IPWREP	SN74LVC74AQPWREP	V62/04652-02YE	V62/06622-01XE
SN74AHC00MPWREP	SN74LVC86AQPWREP	V62/04653-01YE	V62/06622-04XE
SN74AHC02MPWREP	SN74LVC8T245MPWREP	V62/04654-01XE	V62/06623-01YE
SN74AHC04MPWREP	SN74LVT125QPWREP	V62/04654-02XE	V62/06624-01YE
SN74AHC04MPWREPG4	SN74LVT8996IPWREP	V62/04655-01YE	V62/06658-01XE
SN74AHC08MPWREP	SN74LVTH125IPWREP	V62/04655-02YE	V62/06660-01XE
SN74AHC125MPWREP	SN74LVTH240IPWREP	V62/04656-01XE	V62/06662-01XE
SN74AHC14MPWREP	SN74LVTH241IPWREP	V62/04657-01YE	V62/07619-01XE
SN74AHC244MPWREP	SN74LVTH244AQPWREP	V62/04657-02YE	V62/07630-01XE
SN74AHC244MPWREPG4	SN74LVTH245AIPWREP	V62/04658-01YE	V62/08613-01XE
SN74AHC245MPWREP	SN74LVTH273IPWREP	V62/04659-01YE	V62/08614-01XE
SN74AHC32MPWREP	SN74LVTH373IPWREP	V62/04660-01YE	V62/08615-01XE
SN74AHC74MPWREP	SN74LVTH374IPWREP	V62/04660-02YE	V62/08622-01XE
SN74AHCT00MPWREP	SN74LVTH543IPWREP	V62/04661-01YE	V62/09605-01XE
SN74AHCT08MPWREP	SN74LVTH573IPWREP	V62/04661-02YE	V62/09606-01XE
SN74AHCT125QPWREP	SN74LVTH574IPWREP	V62/04662-01YE	V62/09615-01XE
SN74AHCT126QPWREP	SN74LVTH646IPWREP	V62/04663-01YE	V62/10603-01XE
SN74AHCT138MPWREP	SN74LVTH652IPWREP	V62/04664-01XE	XTHS4524MDBTEP
SN74AHCT14MPWREP	SN75976A1MDGGREP	V62/04665-01YE	XTHS4524MDBTREP
SN74AHCT244MPWREP	THS1206MDAREP	V62/04666-01YE	CDCV304TPWREP
SN74AHCT32MPWREP	TLC2274AMPWREP	V62/04667-01YE	MSP430G2231QPW1EP
SN74AHCT74MPWREP	TLC2274MPWREP	V62/04668-01YE	MSP430G2231QPW1REP
SN74AHCU04MPWREP	TLC7701MPWREP	V62/04669-01YE	MSP430G2302IPW1EP
SN74ALVC244IPWREP	TLC7701MPWREPG4	V62/04669-02YE	MSP430G2302IPW1REP
SN74HC02QPWREP	TLC7701QPWREP	V62/04670-01YE	MSP430G2302PW14REP
SN74HC10QPWREP	TLC7705QPWREP	V62/04671-01XE	MSP430G2332QPW2EP
SN74HC165QPWREP	TLC7733MPWREP	V62/04672-01XE	MSP430G2332QPW2REP
SN74HC244QPWREP	TLC7733MPWTEP	V62/04673-01XE	SN65HVD09IDGGREP

SN74HC244QPWREPG4	TLC7733QPWREP	V62/04674-01XE	SN65HVD09IDGGREP
SN74HC595MPWREP	TLV2464AMPWREP	V62/04675-01XE	THS4524MDBTEP
SN74HC74MPWREP	TLV2548MPWREP	V62/04676-01XE	THS4524MDBTEP
SN74HCT244QPWREP	TLV2556MPWREP	V62/04677-01XE	THS4524MDBTEP
SN74LV04ATPWREP	TLV2556MPWREPG4	V62/04678-01XE	V62/12607-01XE
SN74LV08AMPWREP	TLV5614MPWREP	V62/04679-01XE	V62/12607-01XE
SN74LV08ATPWREP	TPS5120MDBTREP	V62/04680-01XE	V62/12612-01XE
SN74LV11ATPWREP	TPS5120QDBTREP	V62/04681-01XE	V62/12612-01XE
SN74LV123ATPWREP	V62/03604-01YE	V62/04683-01YE	V62/12625-01XE
SN74LV14AMPWREP	V62/03605-01YE	V62/04684-01YE	V62/12625-01XE-T
SN74LV14AMPWREPG4	V62/03607-02YE	V62/04687-02YE	
SN74LV14ATPWREP	V62/03609-01XE	V62/04688-01YE	

Qualification Data Approved (03/12/2012)

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: 20Z45DBTRR1MC (MSL2-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4211471
# Pins-Designator, Family:	38-DBT, TSSOP	Mount Compound:	4211470
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Diameter, Au

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	-	-

Notes: * Preconditioning sequence: Level 2-260C.

Qual Vehicle 2 : 7A3T16212DGVR (MSL 1-260C)

Package Construction Details

Assembly Site:	TI Malaysia	Mold Compound:	4211471
# Pins-Designator, Family:	56-DGV, TVSOP	Mount Compound:	4211470
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Diameter, Au

Qualification: ☐ Plan ☒ Test Results

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
Flammability	Method A - UL94V-0	5/0	5/0	5/0
Flammability	Method B - IEC 695-2-2	5/0	5/0	5/0
Flammability	Method C - UL1694	5/0	5/0	5/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0

Notes: * Preconditioning sequence: Level 1-260C.

Qual Vehicle 3 : CDCE706PWR (MSL1-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	20-PW, SOIC	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Diameter, Au	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	-	Pass	-	-
*High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 1-260C.				
Qual Vehicle 4 : E8722DGG (MSL1-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	64-DDG, TSSOP	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.15 Mil Diameter, Au	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	
*High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	
Flammability	Method A - UL94V-0	5/0	-	
Flammability	Method B - IEC 695-2-2	5/0	-	
Flammability	Method C - UL1694	5/0	-	
Manufacturability	(per mfg. Site specification)	Pass	Pass	
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	
Notes: * Preconditioning sequence: Level 1-260C.				
Qual Vehicle 5: SN0610001DGGR (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4211471	
# Pins-Designator, Family:	48-DGG, TSSOP	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Diameter, Au	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
*Biased Temp and Humidity	85C/85%RH (1000 Hrs)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	-	-
Notes: * Preconditioning sequence: Level 2-260C.				

Qual Vehicle 6: SN65C1168PWR (MSL1-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	16-PW, TSSOP	Mount Compound:	4211470	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Diameter, Cu	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cycle)	77/0	77/0	77/0
*Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 1 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 1-260C.				
Qual Vehicle 7: SN75976A2DGG (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4211471	
# Pins-Designator, Family:	56-DGG, TSSOP	Mount Compound:	4211470	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.95 Mil Diameter, Au	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +5/-0C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 2-260C.				
Qual Vehicle 8: TAS5086DBT (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4211471	
# Pins-Designator, Family:	38-DBT, TSSOP	Mount Compound:	4211470	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.80 Mil Diameter, Cu	
Qualification: ☐ Plan ☒ Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Steady-state Life Test	140C (480 Hrs)	77/0	77/0	77/0
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
*Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 2 @ 260C peak +0/-5C)	12/0	12/0	12/0
Notes: * Preconditioning sequence: Level 2-260C.				

Qual Vehicle 9: TCA9539PWR (MSL1-260C)					
Package Construction Details					
Assembly Site:	TI Malaysia	Mold Compound:	4211471		
# Pins-Designator, Family:	24-PW, TSSOP	Mount Compound:	4211470		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.70 Mil Diameter, Au		
Qualification: ☐ Plan ☒ Test Results					
Reliability Test	Conditions	Sample Size / Fail			
		Lot#1	Lot#2	Lot#3	
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0	
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Moisture Sensitivity	(level 1 @ 260C peak +0/-5C)	12/0	12/0	12/0	
Notes: * Preconditioning sequence: Level 1-260C.					
Qual Vehicle 10: TPIC1353DBTRG4 (MSL2-260C)					
Package Construction Details					
Assembly Site:	TI Taiwan	Mold Compound:	4211471		
# Pins-Designator, Family:	44-DBT, TSSOP	Mount Compound:	4211470		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.31 Mil Diameter, Cu		
Qualification: ☐ Plan ☒ Test Results					
Reliability Test	Conditions	Sample Size / Fail			
		Lot#1	Lot#2	Lot#3	
Steady-state Life Test	140C (480 Hrs)	77/0	77/0	77/0	
*Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0	
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0	
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Moisture Sensitivity	(level 2 @ 260C peak +0/-5C)	12/0	12/0	12/0	
Notes: * Preconditioning sequence: Level 2-260C.					
Qual Vehicle 11: UCC5672PWPTR (MSL1-260C)					
Package Construction Details					
Assembly Site:	TI Malaysia	Mold Compound:	4211471		
# Pins-Designator, Family:	28-pw, TSSOP	Mount Compound:	4211470		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Diameter, Au		
Qualification: ☐ Plan ☒ Test Results					
Reliability Test	Conditions	Sample Size / Fail			
		Lot#1	Lot#2	Lot#3	
*High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0	
*Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
*T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Moisture Sensitivity	(level 1 @ 260C peak +0/-5C)	12/0	12/0	12/0	
Notes: * Preconditioning sequence: Level 1-260C.					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com